



## Product Change Notification / ALAN-08KOOJ271

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**Date:**

04-Aug-2022

**Product Category:**

32-bit Microcontrollers

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 4767 Final Notice: Qualification of ANAP as an additional assembly site for selected Atmel AT91SAM7S1xx and AT91SAM7S2xx device families in 64L LQFP (10x10x1.4mm) package.

**Affected CPNs:**

[ALAN-08KOOJ271\\_Affected\\_CPN\\_08042022.pdf](#)  
[ALAN-08KOOJ271\\_Affected\\_CPN\\_08042022.csv](#)

**Notification Text:**

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of ANAP as an additional assembly site for selected Atmel AT91SAM7S1xx and AT91SAM7S2xx device families in 64L LQFP (10x10x1.4mm) package.

**Pre and Post Change Summary:**

	Pre Change	Post Change
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<b>Assembly location</b>		ASE Inc. (ASEK)	ASE Inc. (ASEK)	Amkor Technology Philippine (P1/P2), INC. (ANAP)
<b>Bond wire material</b>		CuPdAu	CuPdAu	CuPdAu
<b>Die attach material</b>		CRM-1076WA	CRM-1076WA	3230
<b>Mold compound material</b>		G631HQ	G631HQ	G631HQ
<b>Lead-frame</b>	<b>Material</b>	C7025	C7025	C194
	<b>Process</b>	Stamped	Stamped	Etched
	<b>Paddle Size</b>	250x250 mils	250x250 mils	295x295 mils
	See pre and post change comparison			

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve productivity by qualifying ANAP as an additional assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**September 1, 2022 (date code: 2236)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	August 2022				September 2022				
Workweek	3 2	3 3	3 4	35	36	37	38	39	40
Qual Report Availability	X								
Final PCN Issue Date	X								
Estimated Implementation Date					X				

**Method to Identify Change:**Traceability Code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**

**July 27, 2021:** Issued initial notification

**August 25, 2021:** Re-issued initial notification to update the molding compound material from G700Y to G631HQ for ANAP assembly site in PCN letter and Qual plan. Updated the Pre and Post change comparison file to reflect the lead frame information only for ASEK and ANAP.

**August 4, 2022:** Issued final notification. Qualification report attached. Provided estimated first ship date to be on September 1, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_ALAN-08KOOJ271\\_Pre and Post Change\\_Summary.pdf](#)

[PCN\\_ALAN-08KOOJ271\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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